

IN THE CLAIMS

Please amend the claims to read as follows:

1 1. (Twice Amended) A method of marking a chip having surfaces comprising the following  
2 steps:  
3 forming internal marking indicia on a marking location upon an exterior surface of the  
4 chip for identification of the chip, and  
5 forming a non-black, optically transmissive encapsulating material over at least the  
6 marking location on the one exterior surface of the chip which non-black, optically  
7 transmissive material cannot be easily scraped off of the chip for prevention of replacement of  
8 the internal marking indicia by different markings.

Bx / SUB C2  
1 3. (Twice Amended) The method of claim 1 wherein the non-black, optically transmissive  
2 encapsulating material is a protective encapsulating material adapted to provide protection  
3 from damage as the result of environmental and handling factors.

B5 / SUB C3  
1 6. (Twice Amended) The method of claim 1 wherein the non-black, optically transmissive  
2 material comprises a material such as epoxy which prevents remarking indicia or  
3 identification marks on the chip.

B6 / SUB C4  
1 12. (Twice Amended) A method of marking a chip having surfaces comprising:  
2 forming internal marking indicia on a marking location upon an exterior surface of the  
3 chip, and  
4 forming a non-black, optically transparent material colored with a particular color over  
5 at least the marking location on that exterior surface of the chip wherein the material colored  
6 with the particular color together with the marking indicia represents identification of the chip  
7 which non-black, optically transparent, colored material cannot be easily scraped off of the  
8 chip for prevention of replacement of the internal marking indicia by different markings.

13. (Twice Amended) A chip comprising:

the chip having exterior surfaces,  
internal marking indicia formed on a marking location upon an exterior surface  
of the chip for identification of the chip, and  
a non-black, optically transmissive material formed over at least the marking location  
on the one exterior surface of the chip which non-black, optically transmissive material cannot  
be easily scraped off for prevention of replacement of the internal marking indicia by different  
markings.

22. (Twice Amended) An electronic integrated circuit chip comprising:

a semiconductor, integrated circuit chip having surfaces including a planar front  
surface, a planar back surface and edges of the chip between the planar surfaces with at least  
one electrical contact site on a surface,

indicia marked upon an exterior marking portion of a surface of the chip for  
identification of the chip,

a non-black layer covering the exterior surface of the chip at least at the exterior  
marking portion thereof, the non-black layer being composed of a colored, optically  
transmissive material which non-black, optically transmissive material cannot be easily  
scraped off of the chip for prevention of replacement of the indicia by different markings and  
for preventing remarking the indicia on the exterior marking surface of the chip, and  
the indicia being visible through the non-black layer.

25. (Twice Amended) A chip comprising:

internal marking indicia formed on a marking location upon an exterior surface of the  
chip, and

a non-black, optically transparent material colored with a particular color formed over  
at least the marking location on that exterior surface of the chip wherein the material colored  
with the particular color together with the marking indicia represents identification of the chip  
which non-black, optically transmissive material cannot be easily scraped off of the chip for